



# Product Change Notification

## 111543 - 01

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# Product Change Notification

**Change Notification #:** 111543 - 01  
**Change Title:** Tray Change from IMT to TFT for Intel® 22x22mm Processor Tray Packed Products, PCN 111543-01, Transport Media, Reason for Revision: Clarify the Performance Characteristics of the Thermoform Tray  
**Date of Publication:** January 24, 2013

## Key Characteristics of the Change:

Transport Media

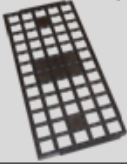




## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jan 24, 2013
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## Description of Change to the Customer:

### Reason for Revision: Clarify the Performance Characteristics of the Thermoform Tray





This PCN is being revised to clarify the performance characteristics of the thermoform tray. The thermoform tray is made of PET (Polyethylene Terephthalate) and has a maximum exposure temperature of 50°C. As stated in the table below, it is recommended that customers retain a quantity of the injection molded trays (IMT) in order to facilitate baking processor units that have exceeded the MET (Manufacturer's Exposure Time). IMTs have a higher Max Temp Exposure rating (140°C). Empty injection molded trays will also be provided upon request for baking purposes if needed. Baking can also be done on thermoform trays at a lower temperature that does not exceed the material Max Temp Exposure per JEDEC standard J-STD-033B.1. Intel encourages customers to manage exposure out of bag to stay within the MET of the product to avoid the extra process step of baking.

	<b>Current</b>	<b>New (as of 9/10/12)</b>	
	Injection Molded Tray (black) 	Thermoform Tray (dark gray) 	*Note: It is recommended that customers retain a quantity of the injection molded tray in order to facilitate baking processor units that have exceeded MET.
TRAY LENGTH	NO CHANGE		
TRAY WIDTH	NO CHANGE		
TRAY HEIGHT	NO CHANGE		
STACKING PITCH	6.35 mm	5.08 mm 	Higher Shipping Density
POCKET #1 LOCATION "X"	NO CHANGE		
POCKET #1 LOCATION "Y"	NO CHANGE		
POCKET PITCH "X"	NO CHANGE		
POCKET PITCH "Y"	NO CHANGE		
SEATING PLANE HEIGHT (FROM BOTTOM OF TRAY)	NO CHANGE		
TRAY WEIGHT	104 grams	61 grams 	Waste Weight Reduction CO2 Emission Reduction
TRAY MATERIAL	MPPO	PET 	Easier to Recycle
MAX TEMP EXPOSURE	140°C	50°C*	
ESD PERFORMANCE	NO CHANGE		

- nTFT material weight is about 1/2 of an IMT, reducing consumption of raw materials
- The reduced weight of nTFT results in a reduction of fuel consumption during transport
- The increased density results in less space required for storage

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Intel is replacing the injection molded tray (IMT) with the thermoform tray (TFT) for the 22mmx22mm products listed below. The tray fill quantity remains the same, 60 units per tray. However, the number of trays in a full box will change as Intel will use a smaller box. See table below.

	Current	Proposed
Tray Material / Type	Injection Molded Tray (black) 	Thermoform Tray (dark gray) 
Tray Stacking Pitch	6.35mm	5.08mm
Inner Box	Full-Height Inner Box 	Half-Height Inner Box 
Moisture Barrier Bag	Full MBB	Partial MBB
Tray Stack	22 trays (+1 cover)	13 trays (+1 cover)
Box Quantity	1320 units	780 units

Customers may need to adjust their order quantities due to the change in the number of units per box. Customers may continue to see both types of trays until current inventory is depleted. During the transition period, customers could see more than one partial box per shipment since two boxes will not be combined if one box is IMT and the other is TFT.

### Customer Impact of Change and Recommended Action:

Customers may want to evaluate this tray with their automated tray handling equipment. Automated equipment may need to be adjusted due to the decreased number of trays per stack and tray stacking pitch. No negative impact is expected at tray handling and pick-n-pack.

If the customer's manufacturing process exceeds the MET of the product and the units must be baked to remove moisture, the bake temperature cannot exceed the Max Temp of the media used for baking. If the bake temperature exceeds 50°C, the units cannot be baked in the thermoform trays and must be baked in an alternative media; e.g., transfer the units to an injection molded tray with a Max Temp rating of 140°C.

If you need samples of this tray, please contact your Intel representative.

### Products Affected / Intel Ordering Codes:

Product Code	S-Spec	MM#
AU80586RE025D S LB6Z	S LB6Z	897938
AU80586GE025D S LB73	S LB73	897939
AU80587RE0251M S LG9Y	S LG9Y	899357

AU80586GF028D S LGL9	S LGL9	900755
CH80566EE025DW S LGPN	S LGPN	901873
CH80566EE014DT S LGPP	S LGPP	901875
CH80566EC005DW S LGPQ	S LGPQ	901876
CH80566EC005DT S LGPR	S LGPR	901877
AU80610004392AAS LBLA	S LBLA	904093
AU80610004653AAS LBMG	S LBMG	904317
AU80610004671AAS LBMH	S LBMH	904318
AU80610003495AAS LBMF	S LBMF	904708
AU80610006240AAS LBX5	S LBX5	907816
AU80610006237AAS LBX9	S LBX9	907817
AU80610006225AAS LBXC	S LBXC	908139
AU80610006291AAS LBXF	S LBXF	908140
AU80610006252AAS LBXD	S LBXD	908151
AU80610006243AAS LBXE	S LBXE	911083
AU80610007485AAS LC3Y	S LC3Y	911820
CT80618007035ABS LJ39	S LJ39	913549
CT80618003201ABS LJ38	S LJ38	913571
CT80618005841ABS LJ37	S LJ37	913650
CT80618005844ABS LJ36	S LJ36	913695
CT80618007035AAS LJ35	S LJ35	913706
CT80618003201AAS LJ34	S LJ34	913720
CT80618005841AAS LJ33	S LJ33	913761
CT80618005844AAS LJ32	S LJ32	913773
AU80610007533AAS LC4C	S LC4C	914458
DF8064101055400S R0D8	S R0D8	915980
DF8064101055647S R0D9	S R0D9	915981
DF8064101050503S R0DA	S R0DA	915983
DF8064101050706S R0DB	S R0DB	915984
DF8064101211300S R0QB	S R0QB	920186
DF8064101213600S R0QC	S R0QC	920189
DF8064101064907S R0QE	S R0QE	920196
DF8064101050506S R0QF	S R0QF	920199
DF8064101050714S R0QG	S R0QG	920202
DF8064101211300S R0VY	S R0VY	922869
DF8064101055400S R0W0	S R0W0	922893
DF8064101050503S R0W1	S R0W1	922908
DF8064101050706S R0W2	S R0W2	922909
DF8064101064908S R0W3	S R0W3	922911
DF8064101213700S R0W4	S R0W4	922916
DF8064101365900S R0W6	S R0W6	922924

## PCN Revision History:

### Date of Revision:

June 12, 2012

January 24, 2013

### Revision Number:

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01

### Reason:

Originally Published PCN

Clarify the Performance  
Characteristics of the Thermoform  
Tray